

ABSTRACT

A photoresist spray coating process for deep trenched substrates. According to one implementation of the invention, the substrate surface is primed with a primer having a water contact angle between forty and fifty degrees. A spray nozzle is moved across the diameter of the substrate at varying speeds to achieve a coat of substantially the same thickness throughout. The photoresist is spray coated on the substrate surface at an angle to the substrate surface to obtain coverage of deep etched features. The photoresist is dissolved in a solvent according to specific dilution ratios to achieve a viscosity range that permits spraying the photoresist evenly in deep etch features while avoiding pull-back.